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FETT Functional Electronic TexTiles

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UNIVERSITY OF Southampton Electronics and Computer Science

Publications

1) Menglong Li, John Tudor, Russel Torah and Steve Beeby "Stress analysis of flexible packaging for the integration of electronic components within woven textiles", 2017 IEEE 67th Electronic Components and Technology Conference (ECTC)

2) Menglong Li, John Tudor, Russel Torah and Steve Beeby "Stress analysis and optimization of flexible electronic packaging for functional electronic textiles", IEEE Transactions on Components, Packaging and Manufacturing Technology. 2017

3) Menglong Li, John Tudor, Jingqi Liu, Komolafe Abiodun, Russel Torah and Steve Beeby "The thickness and material optimization of flexible electronic packaging for functional electronic textile", 2018 IEEE 20th Design, Test, Integration and Packaging of MEMS/MOEMS Symposium

4) Beeby, S., Torah, R., Tudor, J., Li, M., Komolafe, A., & Yang, K. (2018, August). Functional Electronic Textiles: Circuit Integration and Energy Harvesting Power Supplies. In 2018 International Flexible Electronics Technology Conference (IFETC) (pp. 1-3). IEEE.

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5) Li, M. (2018). Electronic packaging for functional electronic textiles (Doctoral dissertation, University of Southampton)

6) Hardy, D., Anastasopoulos, I., Nashed, M. N., Oliveira, C., Hughes-Riley, T., Komolafe, A., ... & Dias, T. (2018, May). An automated process for inclusion of package dies and circuitry within a textile yarn. In *2018 Symposium on Design, Test, Integration & Packaging of MEMS and MOEMS (DTIP)* (pp. 1-5). IEEE.

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8) Hardy, D. A., Anastasopoulos, I., Nashed, M. N., Hughes-Riley, T., Komolafe, A., Tudor, J., ... & Dias, T. (2018). Automated insertion of package dies onto wire and into a textile yarn sheath. *Microsystem Technologies.*

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9) Li, M., Torah, R., Liu, J., Tudor, M., & Beeby, S. (2018). Finite element analysis (FEA) modelling and experimental verification to optimise flexible electronic packaging for e-textiles. *Microsystem Technologies*.

10) Ojuroye, O., Torah, R., & Beeby, S. (2018, May). Improving the integration of e-textile microsystems' encapsulation by modifying PDMS formulation. In *2018 Symposium on Design, Test, Integration & Packaging of MEMS and MOEMS (DTIP)*(pp. 1-6). IEEE.

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13) Komolafe, A., Torah, R., Wei, Y., Nunes-Matos, H., Li, M., Hardy, D., ... & Beeby, S. (2019). Integrating flexible filament circuits for e-textile applications. Advanced Materials Technologies, 4(7), 1900176.

14) Komolafe, A., Torah, R., Nunes-Matos, H., Tudor, M., & Beeby, S. (2019, July). Integration of temperature sensors in fabrics. In 2019 IEEE International Conference on Flexible and Printable Sensors and Systems (FLEPS) (pp. 1-2). IEEE.